



Fast Thyristor
Type TFI473-1600-40

Low switching losses
Low reverse recovery charge
Distributed amplified gate for high di_T/dt

Mean on-state current	I_{TAV}	1600 A
Repetitive peak off-state voltage	V_{DRM}	3800 ÷ 4000 V
Repetitive peak reverse voltage	V_{RRM}	
Turn-off time	t_q	125; 160 μs
V_{DRM}, V_{RRM}, V	3800	4000
Voltage code	38	40
$T_{ij}, ^\circ C$	- 60 ÷ 125	

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions
ON-STATE				
I_{TAV}	Mean on-state current	A	1600 2340	$T_c=85^\circ C$; Double side cooled; $T_c=55^\circ C$; Double side cooled; 180° half-sine wave; 50 Hz
I_{TRMS}	RMS on-state current	A	2512	$T_c=85^\circ C$; Double side cooled; 180° half-sine wave; 50 Hz
I_{TSM}	Surge on-state current	kA	30.0 35.0	180° half-sine wave; 50 Hz ($t_p=10$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=50$ μs ; $di_G/dt=2$ A/ μs
			32.0 37.0	180° half-sine wave; 60 Hz ($t_p=8.3$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=50$ μs ; $di_G/dt=2$ A/ μs
I^2t	Safety factor	$A^2s \cdot 10^3$	4500 6125	180° half-sine wave; 50 Hz ($t_p=10$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=50$ μs ; $di_G/dt=2$ A/ μs
			4245 5680	180° half-sine wave; 60 Hz ($t_p=8.3$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=50$ μs ; $di_G/dt=2$ A/ μs
BLOCKING				
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	3800÷4000	$T_{j\ min} < T_j < T_{j\ max}$; 180° half-sine wave; 50 Hz; Gate open
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	3900÷4100	$T_{j\ min} < T_j < T_{j\ max}$; 180° half-sine wave; 50 Hz; single pulse; Gate open
V_D, V_R	Direct off-state and Direct reverse voltages	V	0.75· V_{DRM} 0.75· V_{RRM}	$T_j=T_{j\ max}$; Gate open

TRIGGERING				
I_{FGM}	Peak forward gate current	A	10	$T_j = T_{j\ max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	8	$T_j = T_{j\ max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/ μ s	2000	$T_j = T_{j\ max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 2 I_{TAV}$; Gate pulse: $I_G = I_{FGM}$; $V_G = 20$ V; $t_{GP} = 50$ μ s; $di_G/dt = 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	$^{\circ}$ C	-60 \div 125	
T_j	Operating junction temperature	$^{\circ}$ C	-60 \div 125	
MECHANICAL				
F	Mounting force	kN	40.0 \div 50.0	
a	Acceleration	m/s ²	50 100	Device unclamped Device clamped

CHARACTERISTICS

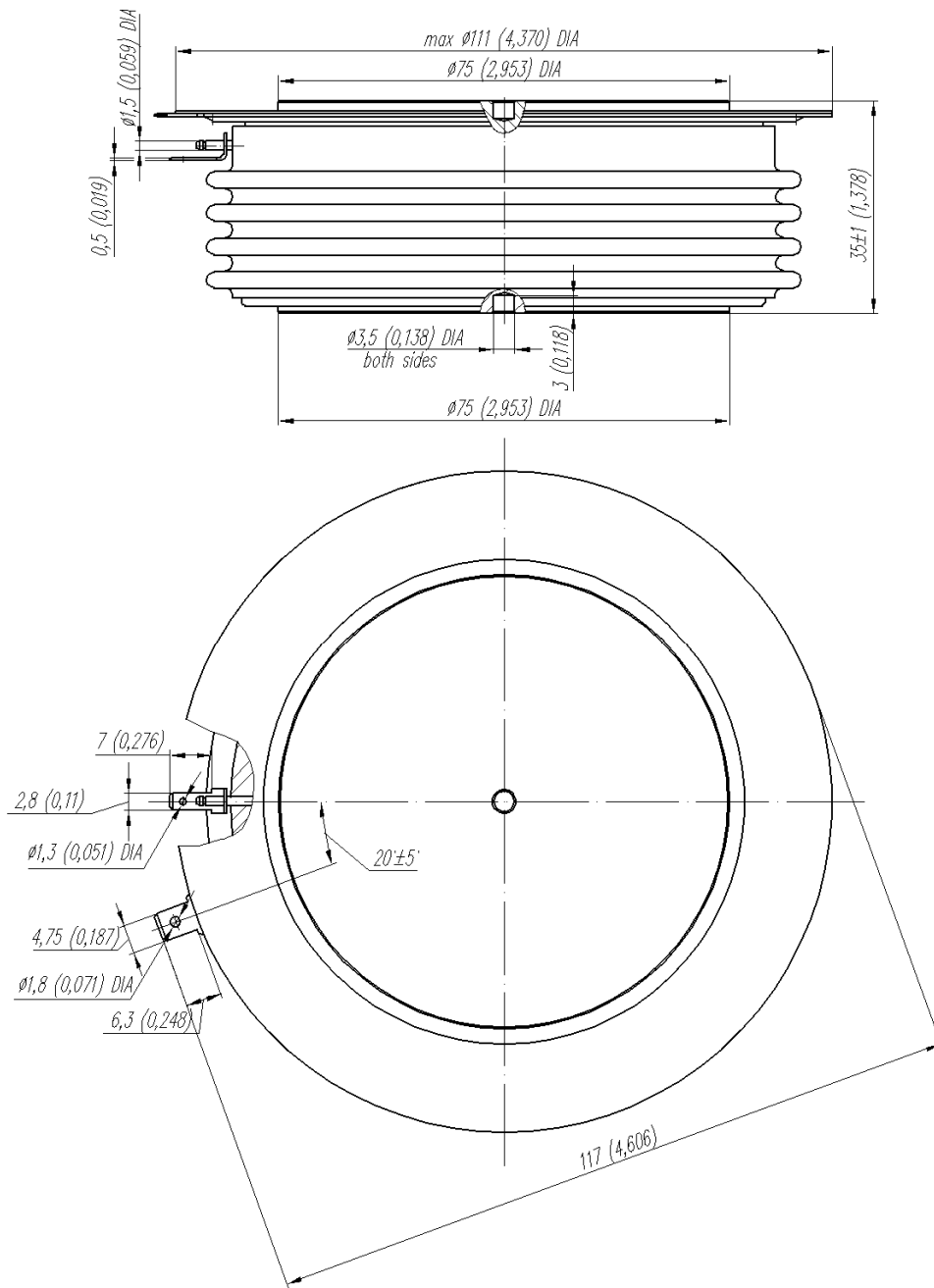
Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V_{TM}	Peak on-state voltage, max	V	2.40 2.70	$T_j = T_{j\ max}$; $I_{TM} = 4000$ A $T_j = 25$ $^{\circ}$ C; $I_{TM} = 5024$ A	
$V_{T(TO)}$	On-state threshold voltage, max	V	1.44	$T_j = T_{j\ max}$;	
r_T	On-state slope resistance, max	m Ω	0.270	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$	
I_H	Holding current, max	mA	1000	$T_j = 25$ $^{\circ}$ C; $V_D = 12$ V; Gate open	
BLOCKING					
I_{DRM} , I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	300	$T_j = T_{j\ max}$; $V_D = V_{DRM}$; $V_R = V_{RRM}$	
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	1000	$T_j = T_{j\ max}$; $V_D = 0.67 \cdot V_{DRM}$; Gate open	
TRIGGERING					
V_{GT}	Gate trigger direct voltage, max	V	5.00 3.00 2.00	$T_j = T_{j\ min}$ $T_j = 25$ $^{\circ}$ C $T_j = T_{j\ max}$	$V_D = 12$ V; $I_D = 3$ A; Direct gate current
I_{GT}	Gate trigger direct current, max	mA	500 300 200	$T_j = T_{j\ min}$ $T_j = 25$ $^{\circ}$ C $T_j = T_{j\ max}$	
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j = T_{j\ max}$; $V_D = 0.67 \cdot V_{DRM}$;	
I_{GD}	Gate non-trigger direct current, min	mA	15.00	Direct gate current	
SWITCHING					
t_{gd}	Delay time	μ s	3.5	$T_j = 25$ $^{\circ}$ C; $V_D = 0.4 \cdot V_{DRM}$; $I_{TM} = I_{TAV}$; Gate pulse: $I_G = I_{FGM}$; $V_G = 20$ V; $t_{GP} = 50$ μ s; $di_G/dt = 2$ A/ μ s	
t_q	Turn-off time ²⁾ , max	μ s	125; 160	$dv_D/dt = 50$ V/ μ s;	$T_j = T_{j\ max}$; $I_{TM} = I_{TAV}$; $di_R/dt = -10$ A/ μ s; $V_R = 100$ V; $V_D = 0.67 V_{DRM}$
			160; 200	$dv_D/dt = 200$ V/ μ s;	
Q_{rr}	Total recovered charge(linear), max	μ C	3000	$T_j = T_{j\ max}$; $I_{TM} = 2000$ A;	
t_{rr}	Reverse recovery time, max	μ s	14	$di_R/dt = -50$ A/ μ s;	
I_{rrM}	Peak reverse recovery current, max	A	430	$V_R = 100$ V	

THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	°C/W	0.0100	Direct current	Double side cooled
R_{thjc-A}			0.0220		Anode side cooled
R_{thjc-K}			0.0180		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	°C/W	0.0020	Direct current	
MECHANICAL					
w	Weight, typ	g	1600		
D_s	Surface creepage distance	mm (inch)	55.13 (2.170)		
D_a	Air strike distance	mm (inch)	25.10 (0.988)		

NOTES		PART NUMBERING GUIDE																												
¹⁾ Critical rate of rise of off-state voltage <table border="1"> <tr> <td>Symbol of group</td> <td colspan="2">A2</td> </tr> <tr> <td>$(dv_D/dt)_{crit}$, V/μs</td> <td colspan="2">1000</td> </tr> </table>		Symbol of group	A2		$(dv_D/dt)_{crit}$, V/ μ s	1000		<table border="1"> <tr> <td>TFI</td> <td>473</td> <td>1600</td> <td>40</td> <td>A2</td> <td>X2</td> <td colspan="2">N</td> </tr> <tr> <td>1</td> <td>2</td> <td>3</td> <td>4</td> <td>5</td> <td>6</td> <td colspan="2">7</td> </tr> </table>							TFI	473	1600	40	A2	X2	N		1	2	3	4	5	6	7	
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²⁾ Turn-off time ($dv_D/dt=50$ V/ μ s) <table border="1"> <tr> <td>Symbol of group</td> <td>X2</td> <td>T2</td> </tr> <tr> <td>t_{qr}, μs</td> <td>125</td> <td>160</td> </tr> </table>		Symbol of group	X2	T2	t_{qr} , μ s	125	160	<ol style="list-style-type: none"> TFI — Fast Thyristor TFIS — Fast Thyristor with Distributed Amplified Gate Design version Mean on-state current, A Voltage code Critical rate of rise of off-state voltage Group of turn-off time ($dv_D/dt=50$ V/μs) Ambient conditions: N – normal; T – tropical 																						
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t_{qr} , μ s	125	160																												

OVERALL DIMENSIONS

Package type: T.F5



All dimensions in millimeters (inches)

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On-state characteristic model (see Fig. 1).

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients	
	T _j = 25°C	T _j = T _{j max}
A	1.799223	1.165741
B	0.106392	0.195115
C	-0.227901	-0.304378
D	0.350140	0.467637

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2).

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where *i* = 1 to *n*, *n* is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time *t*.

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

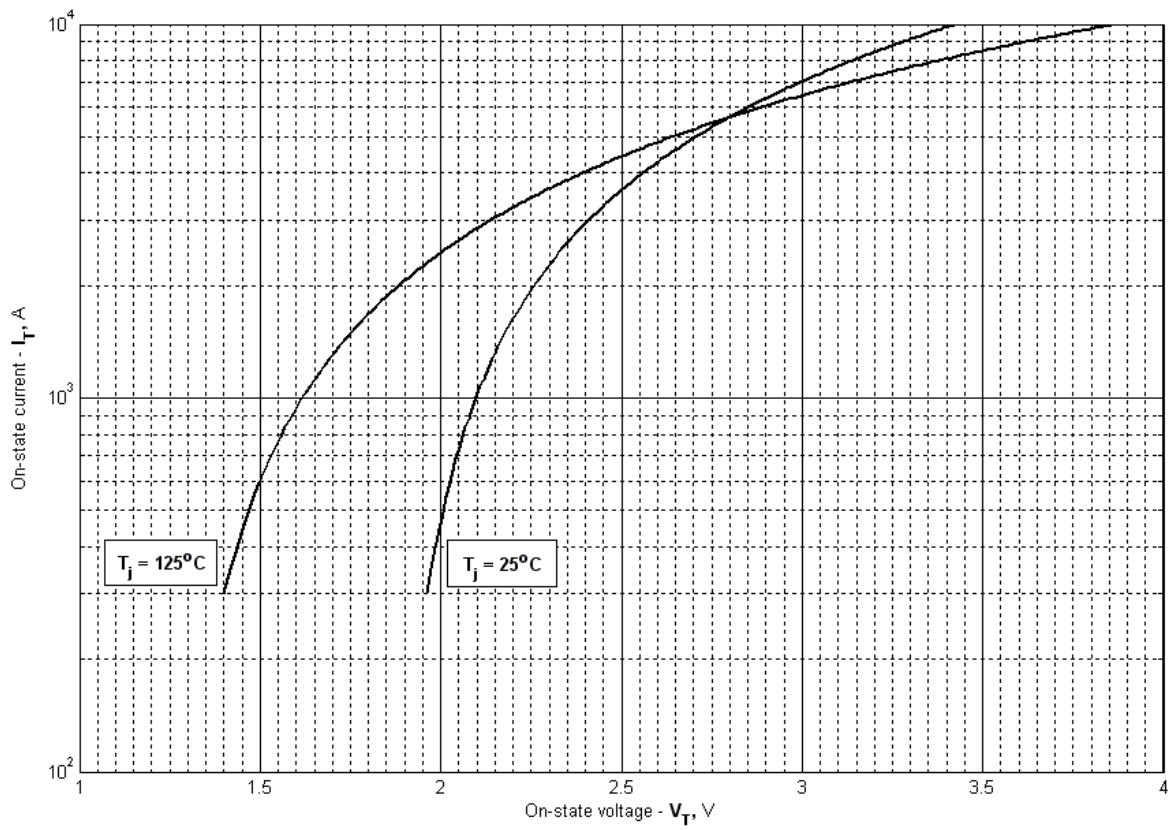
i	1	2	3	4	5	6
R_i, K/W	0.002785	0.003537	0.0005787	0.0006418	0.00009446	0.002362
τ_i, s	2.061	0.07354	0.002615	0.1375	0.0004601	1.210

DC Anode side cooled

i	1	2	3	4	5	6
R_i, K/W	0.01246	0.00478	0.0006333	0.003716	0.0005969	0.00006119
τ_i, s	13.310	1.871	0.2261	0.07337	0.002363	0.0003248

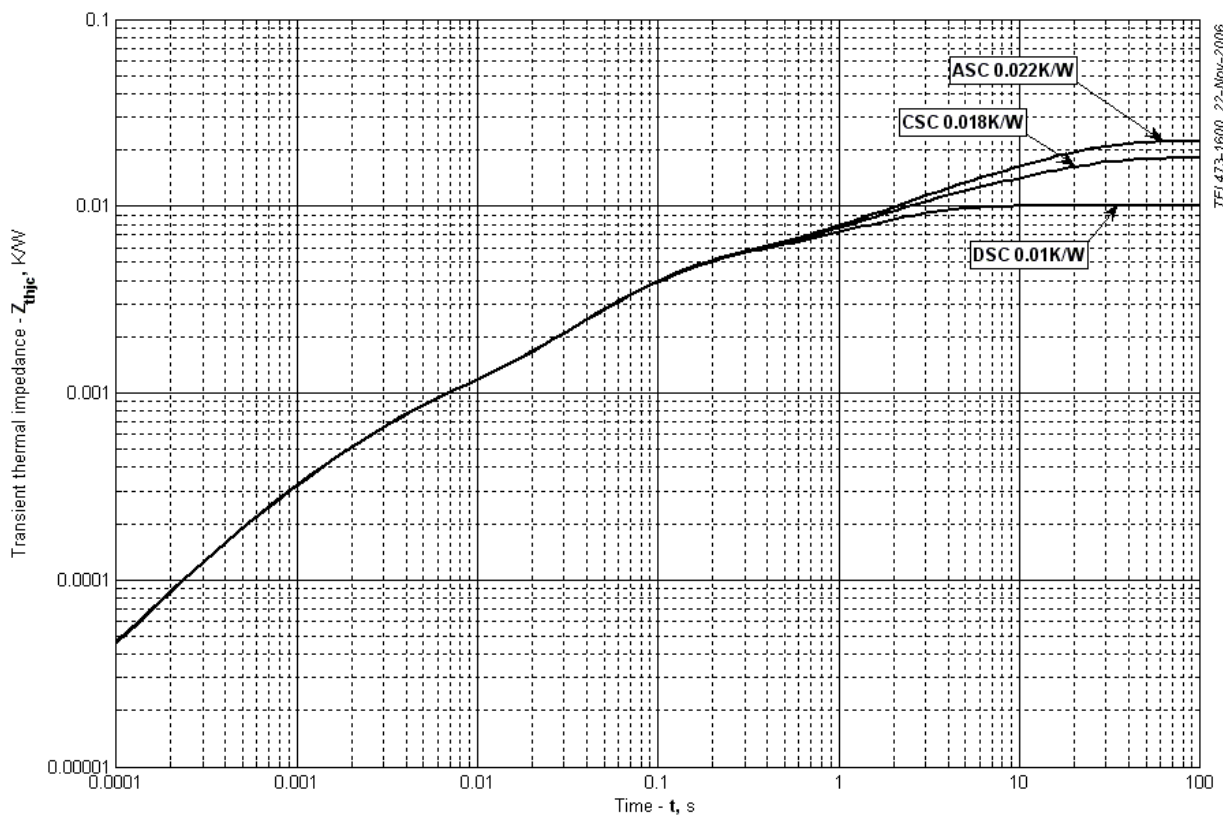
DC Cathode side cooled

i	1	2	3	4	5	6
R_i, K/W	0.008256	0.004771	0.0006239	0.003744	0.0005969	0.00006164
τ_i, s	13.250	1.783	0.2371	0.07347	0.002367	0.000327



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Fig 1 – On-state characteristics of Limit device



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Fig 2 – Transient thermal impedance

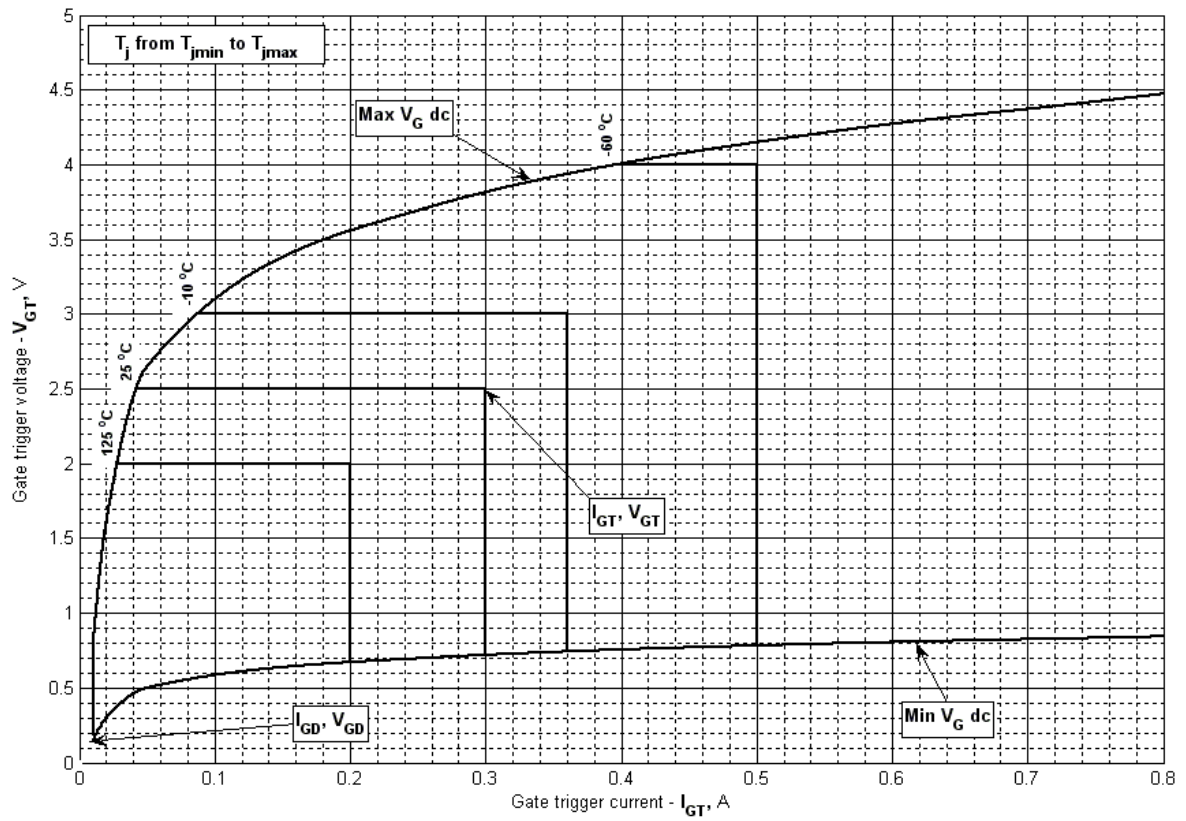


Fig 3 – Gate characteristics – Trigger limits

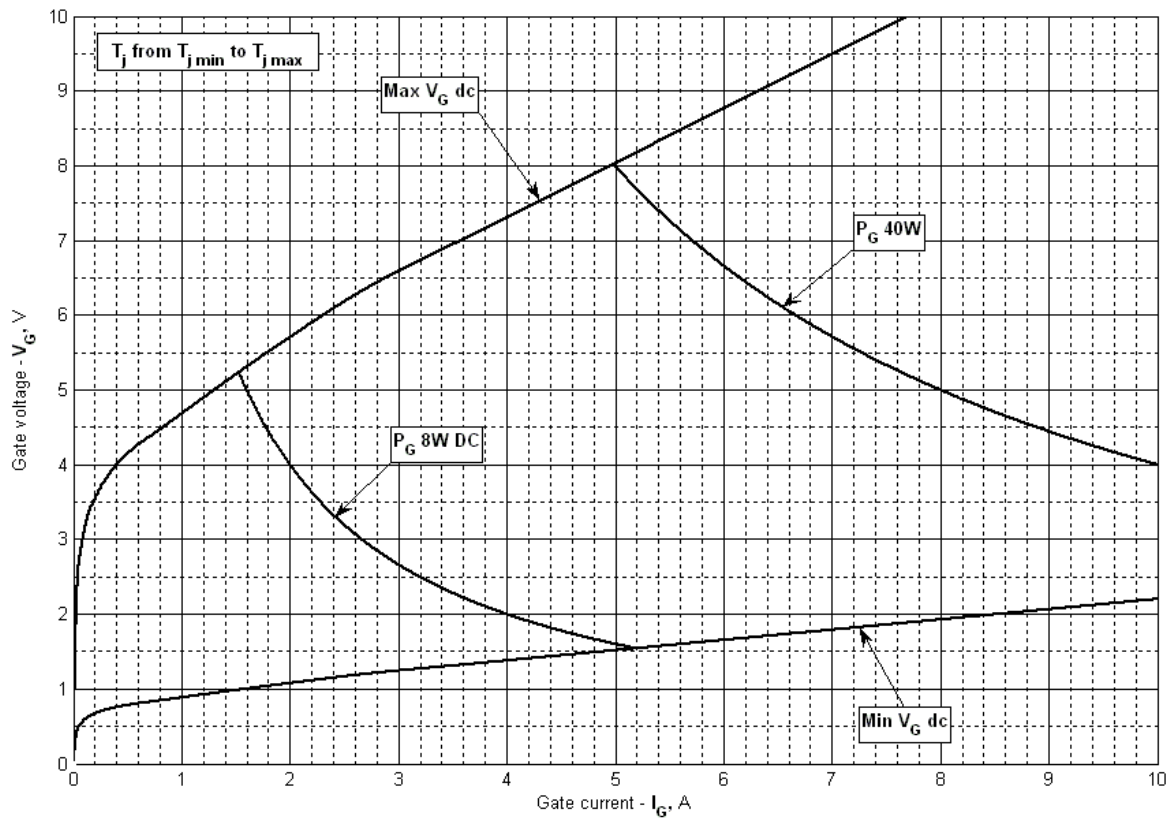


Fig 4 - Gate characteristics –Power curves

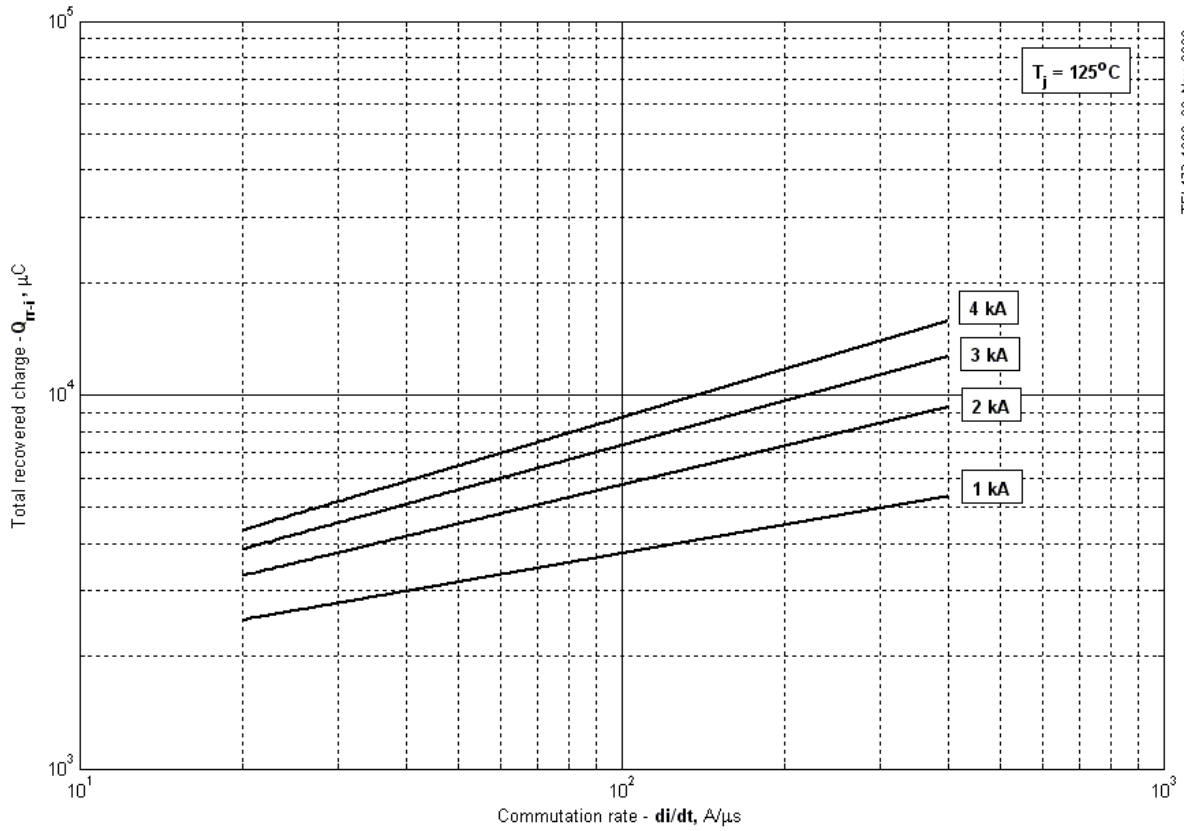


Fig 5 – Total recovered charge, Q_{tr-i} (integral)

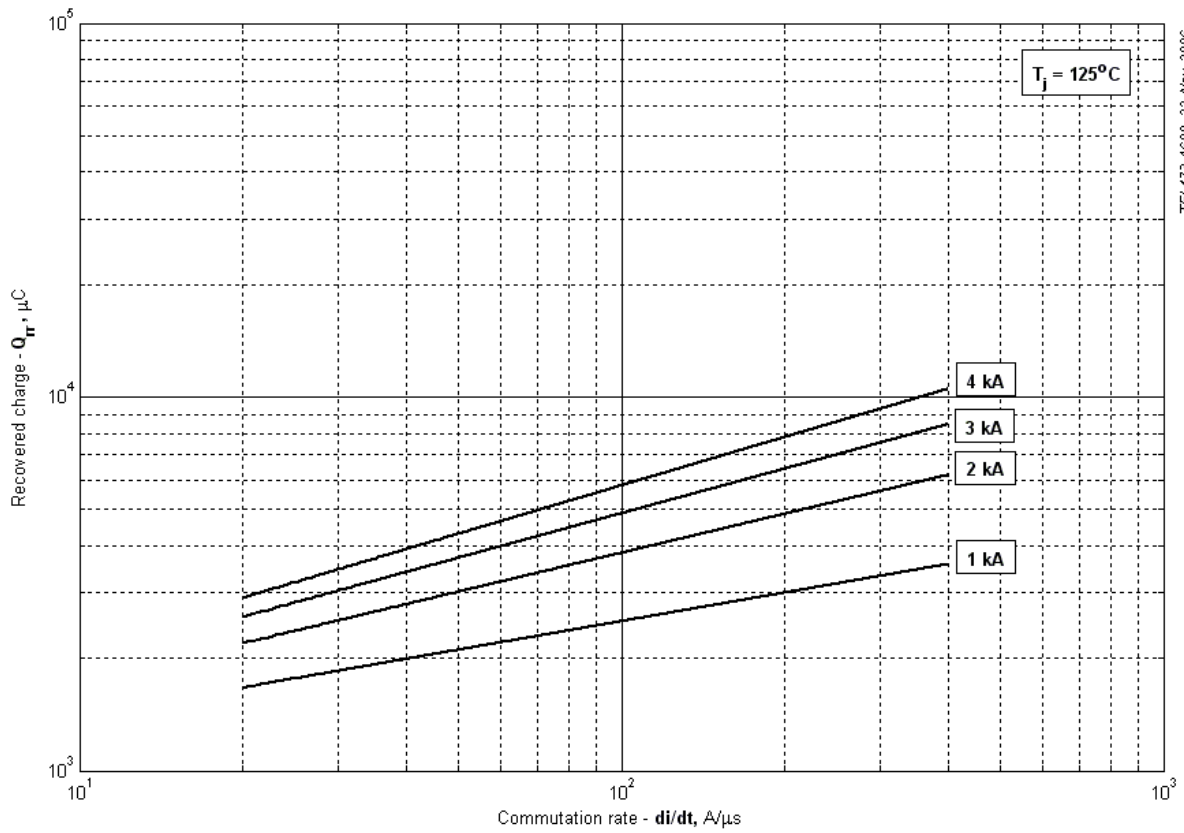


Fig 6 - Recovered charge, Q_{tr} (linear)

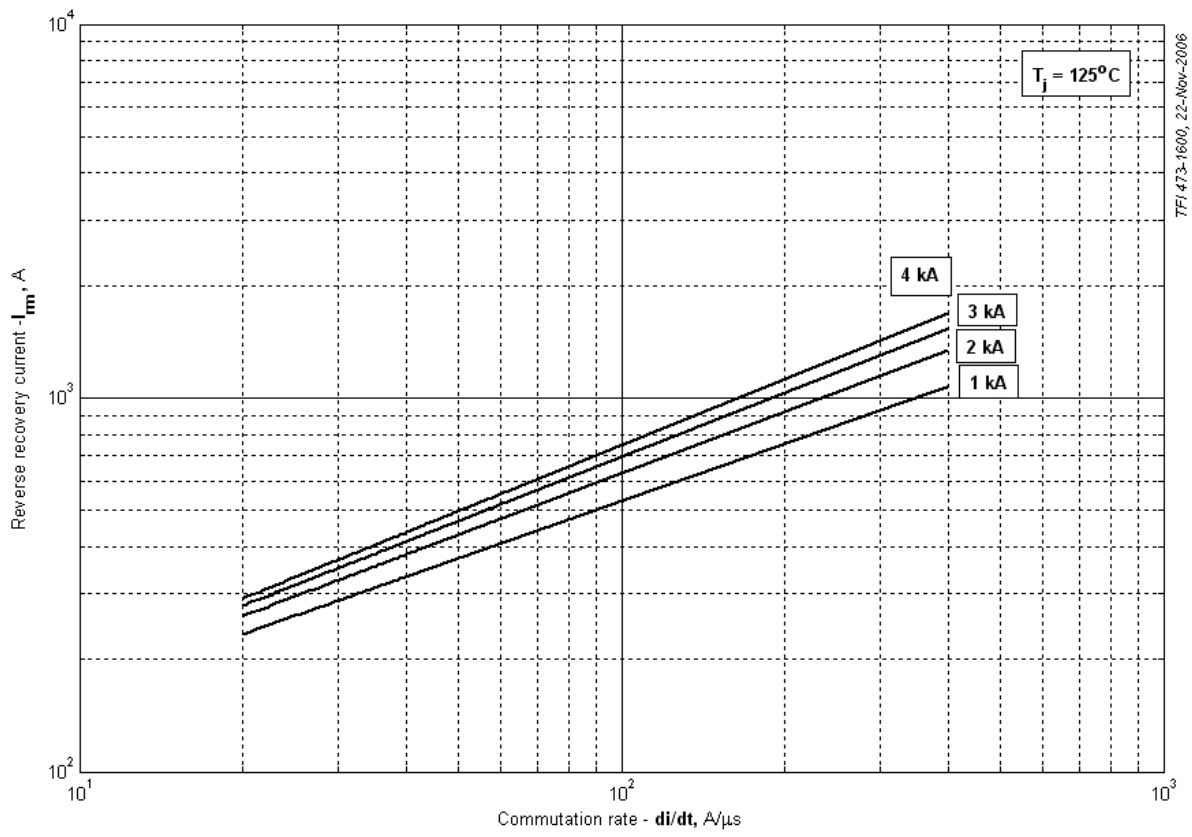


Fig 7 – Peak reverse recovery current, I_{rm}

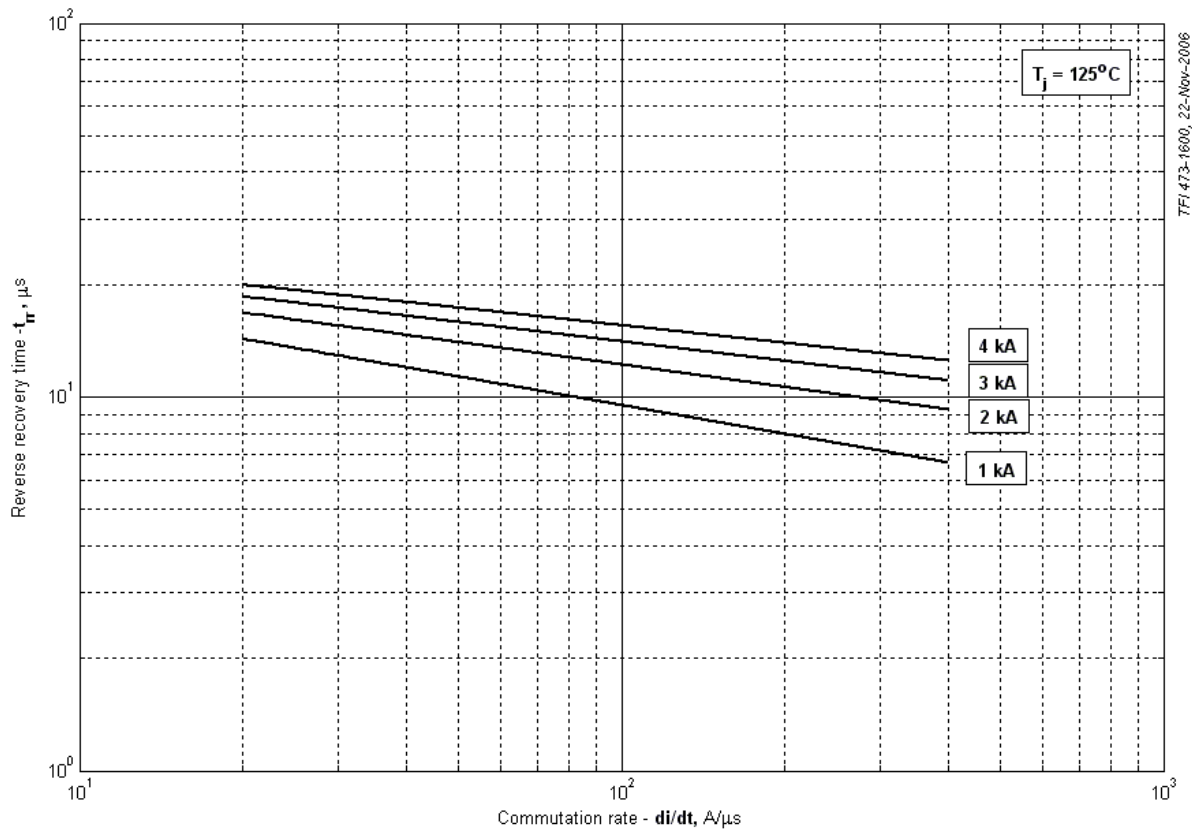


Fig 8 – Maximum recovery time, t_{tr} (linear)

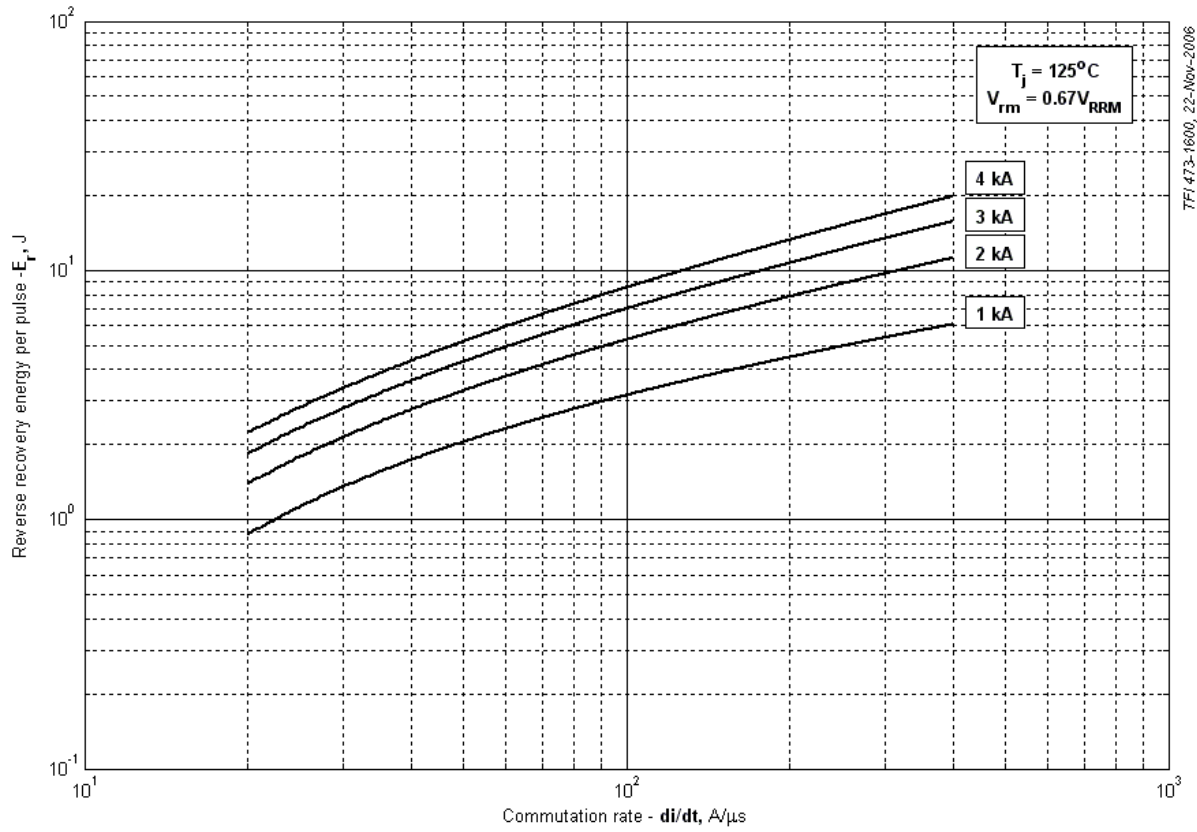


Fig 9 – Reverse recovery energy per pulse

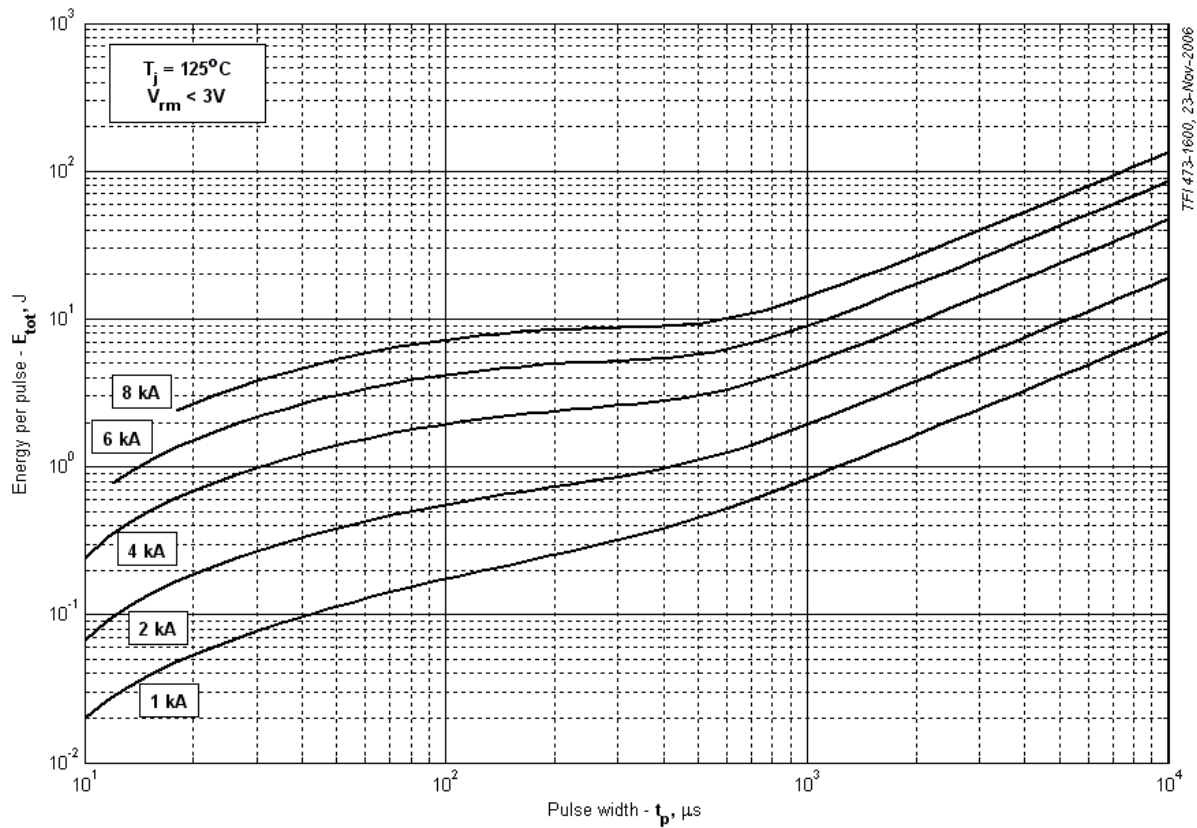


Fig 10 – Sine wave energy per pulse

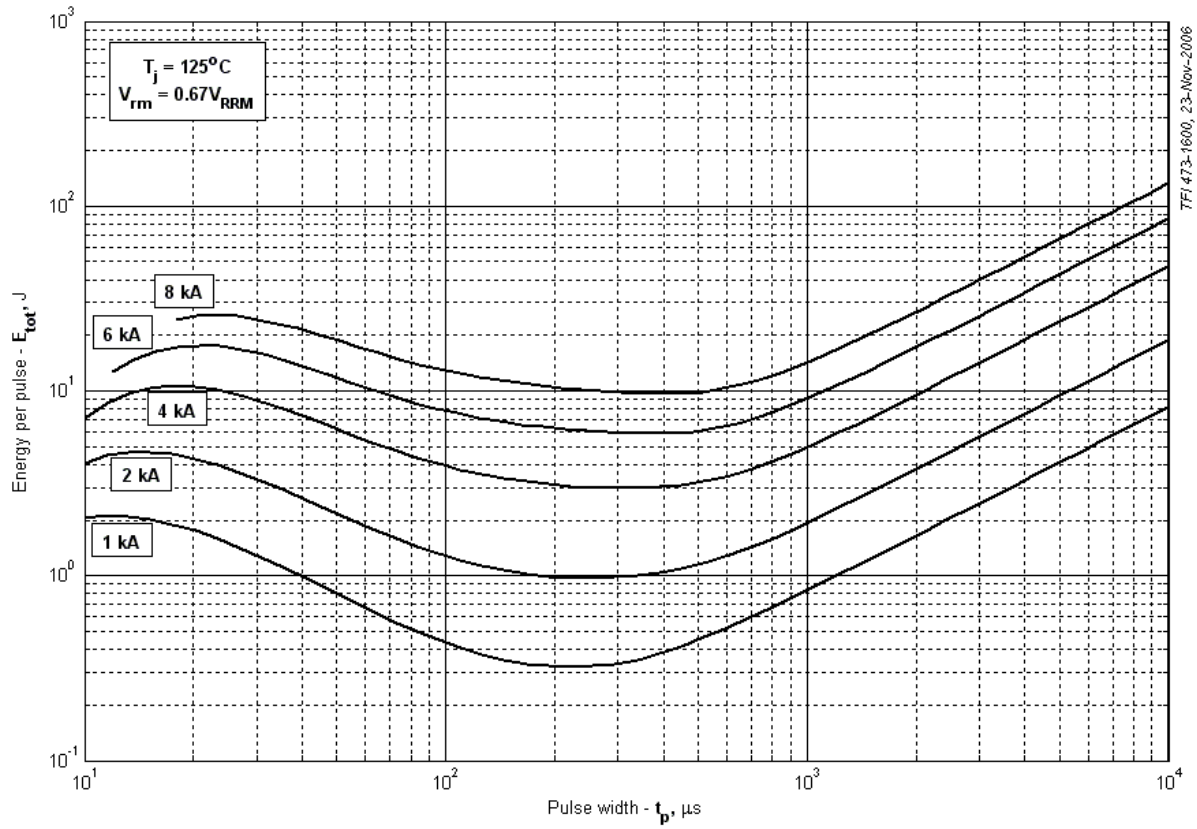


Fig 11 – Sine wave energy per pulse

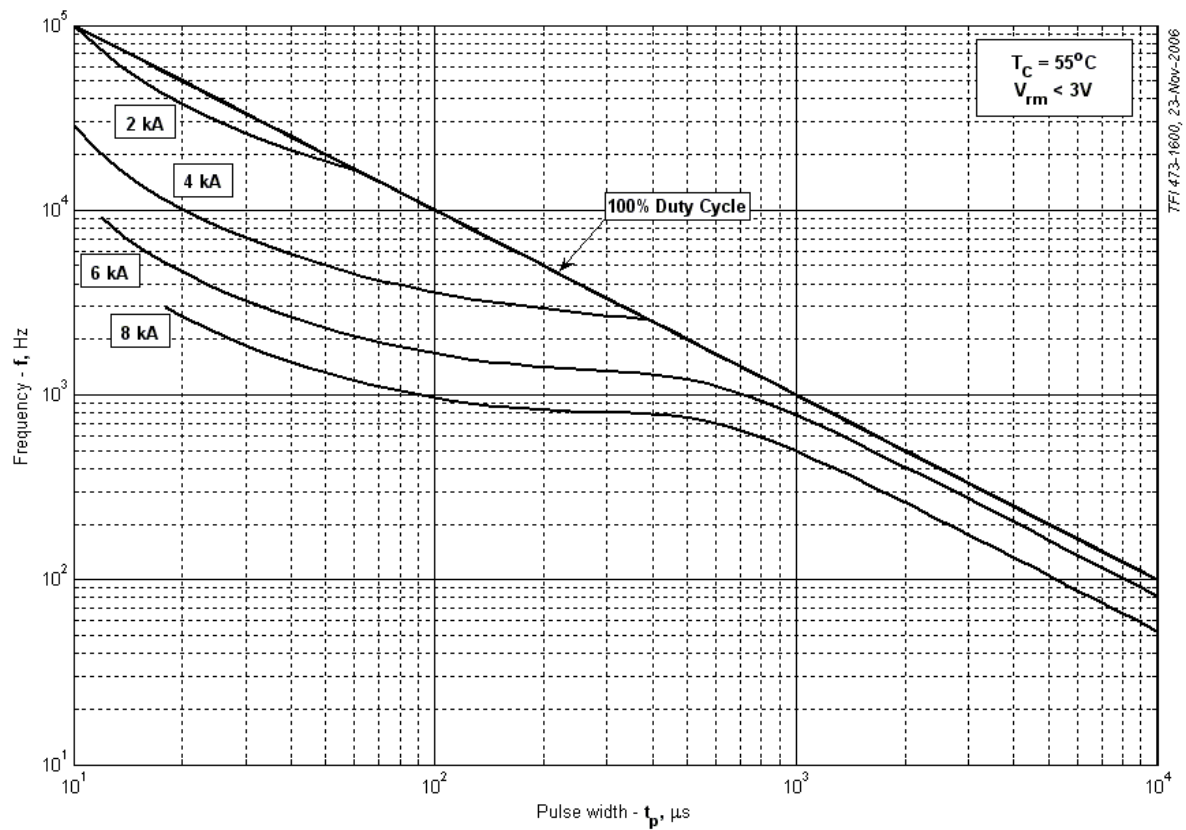


Fig 12 – Sine wave frequency ratings

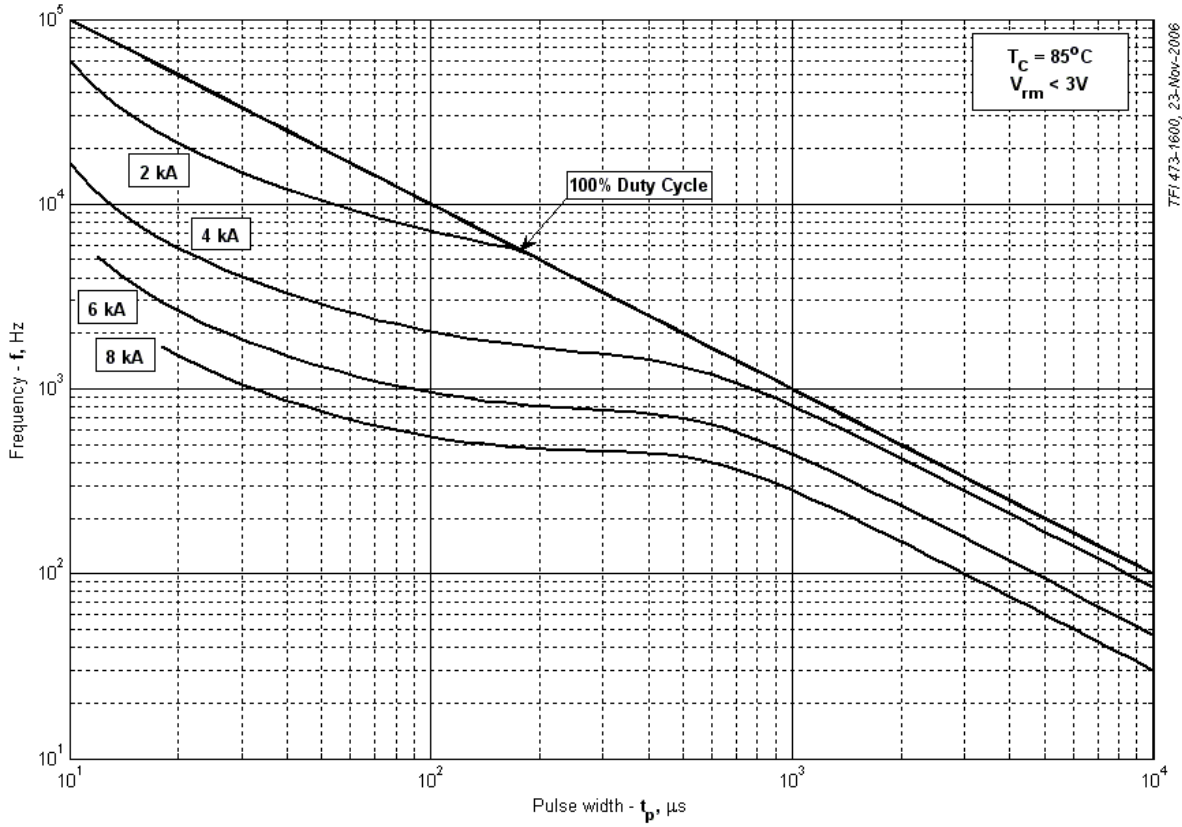


Fig 13 – Sine wave frequency ratings

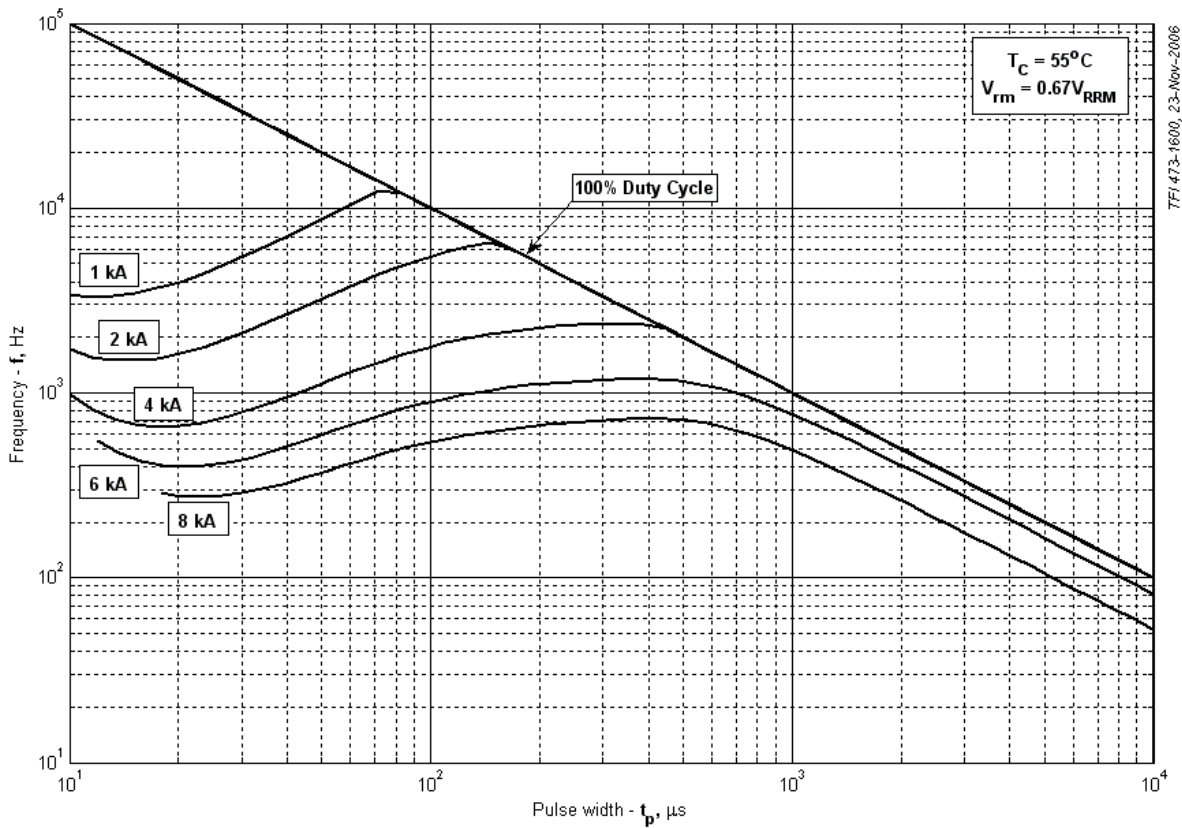
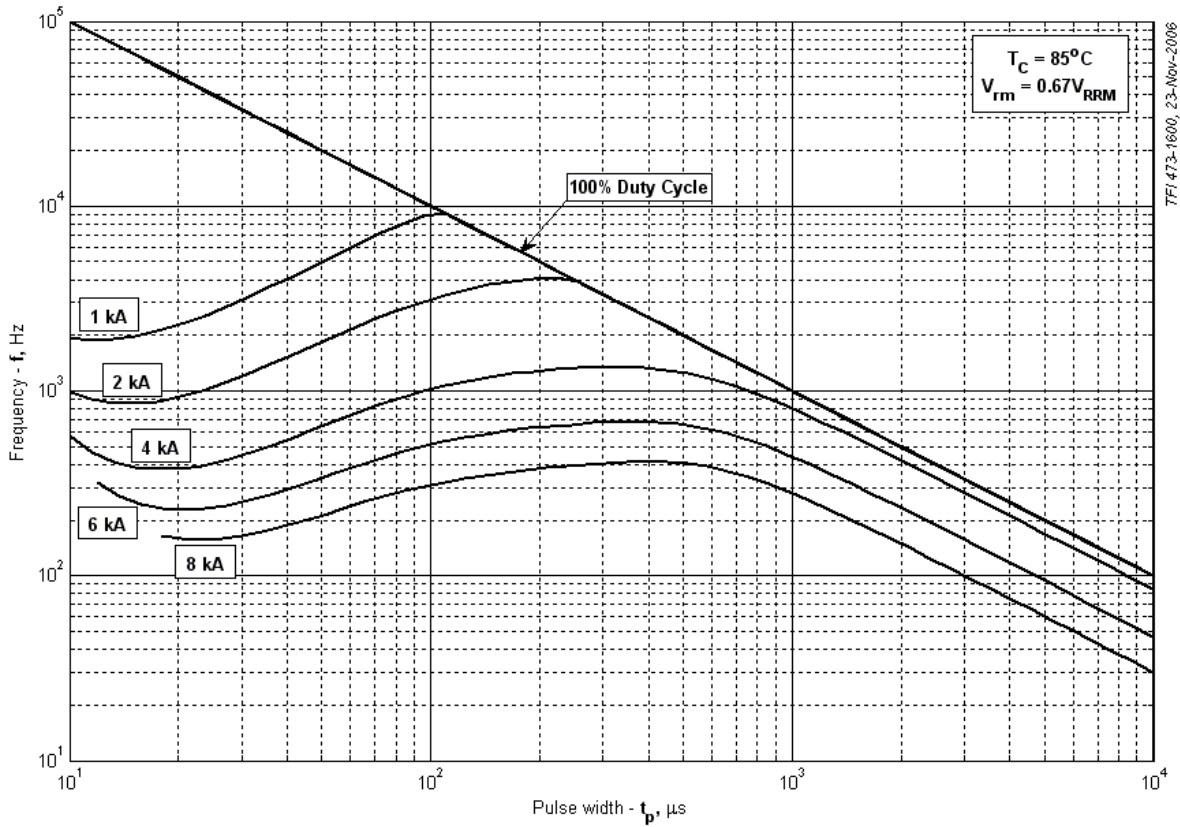
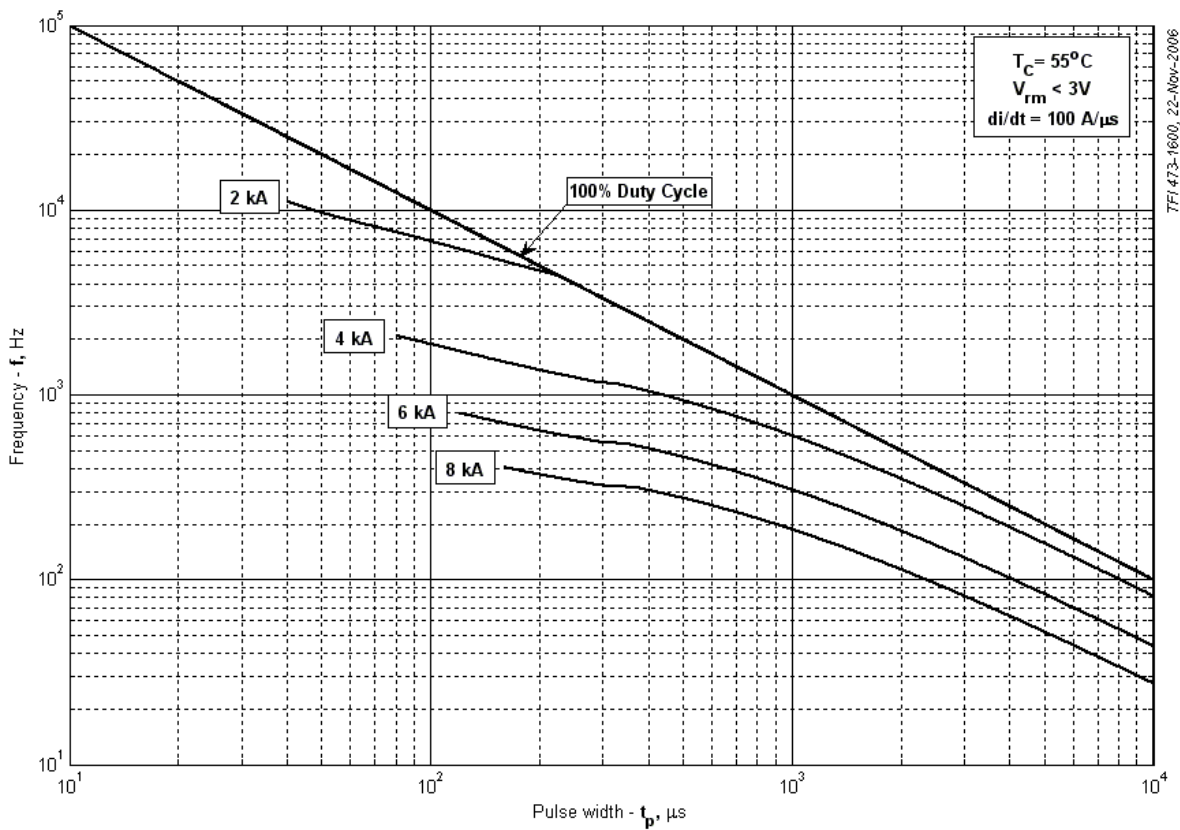


Fig 14 – Sine wave frequency ratings



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Fig 15 – Sine wave frequency ratings



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Fig 16 – Square wave frequency ratings

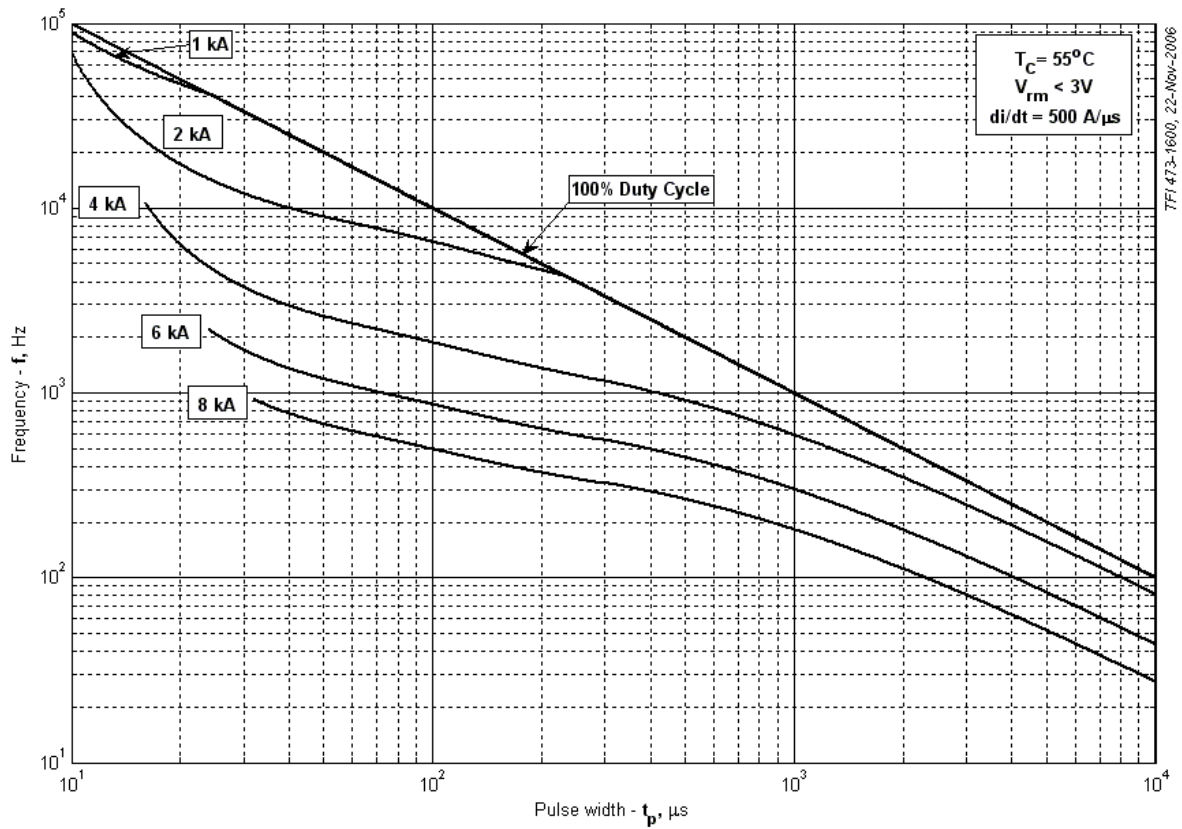


Fig 17 – Square wave frequency ratings

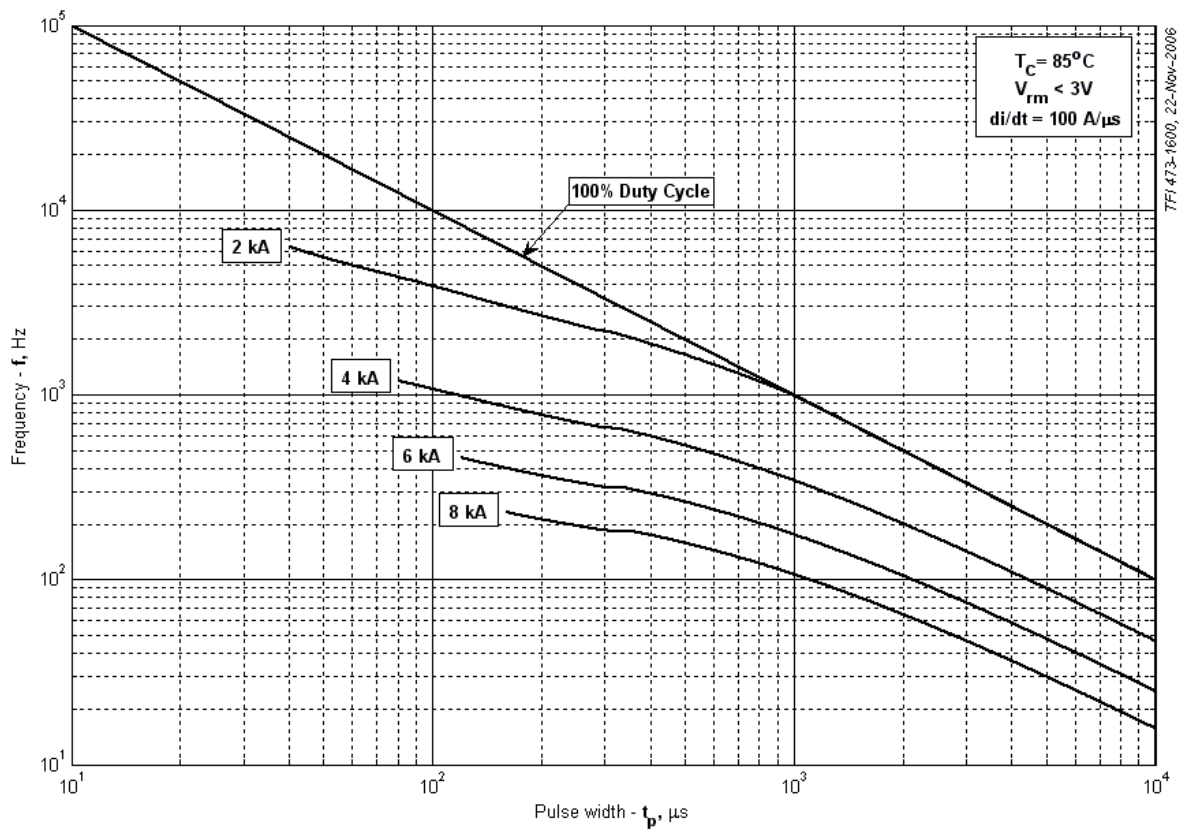


Fig 18 – Square wave frequency ratings

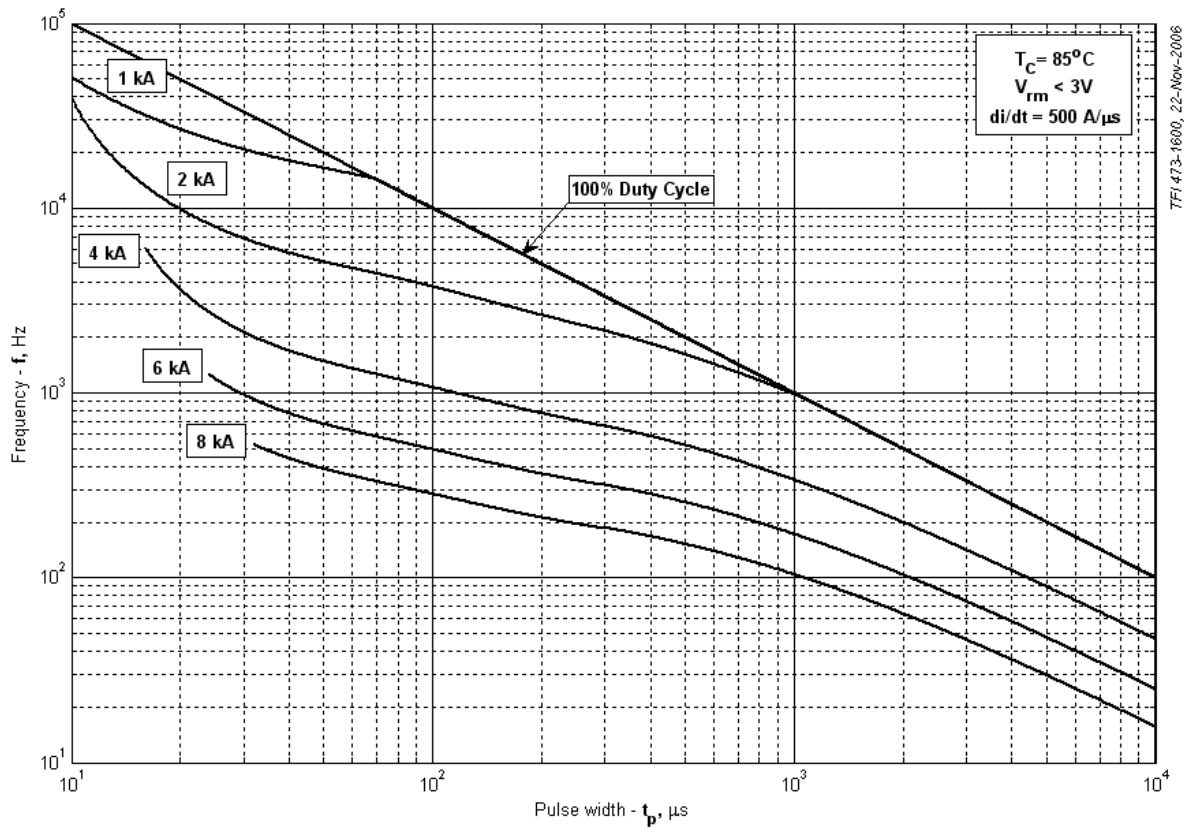


Fig 19 – Square wave frequency ratings

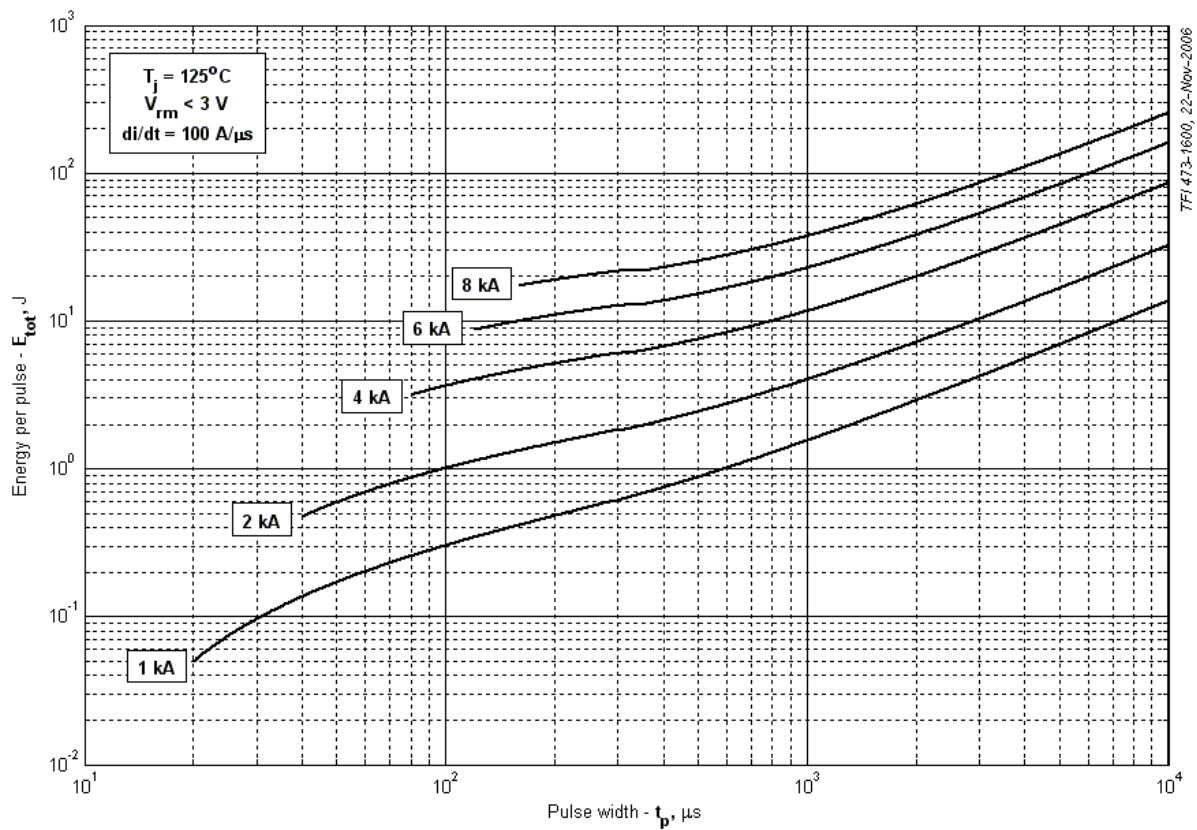


Fig 20 – Square wave energy per pulse

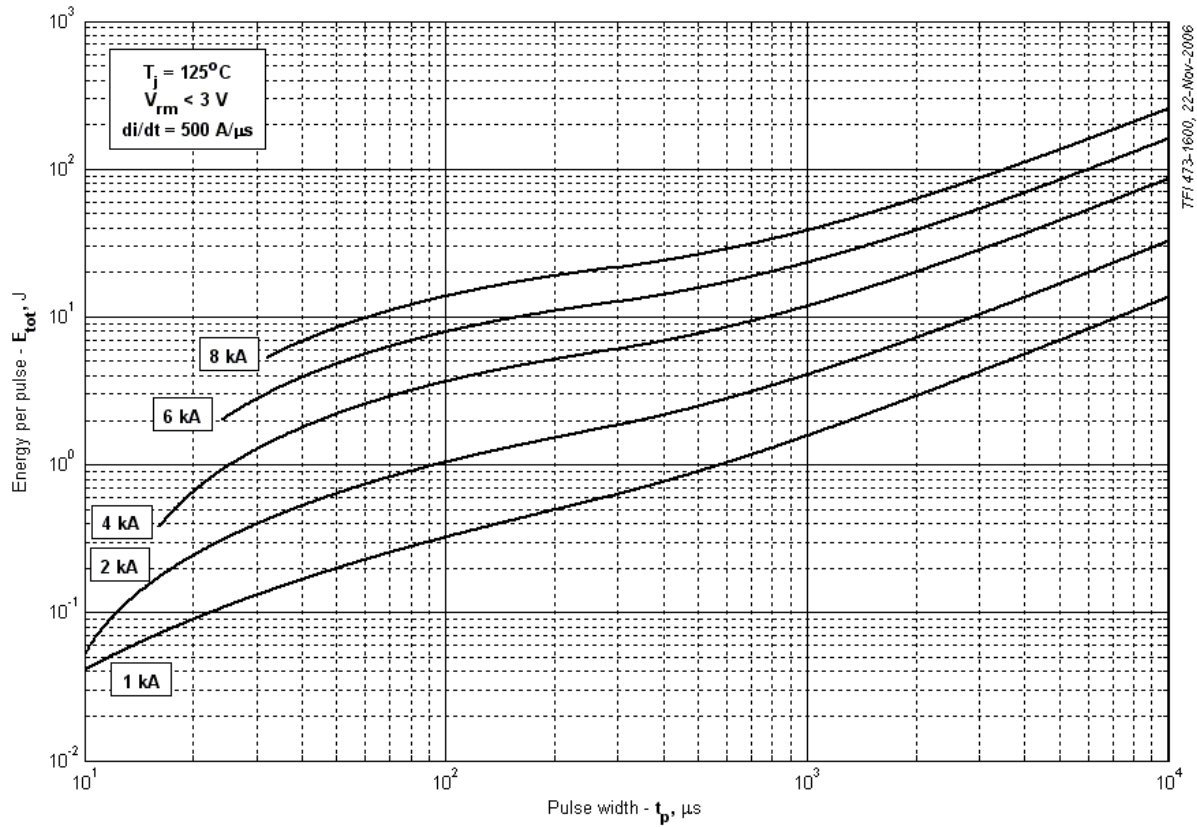


Fig 21 – Square wave energy per pulse

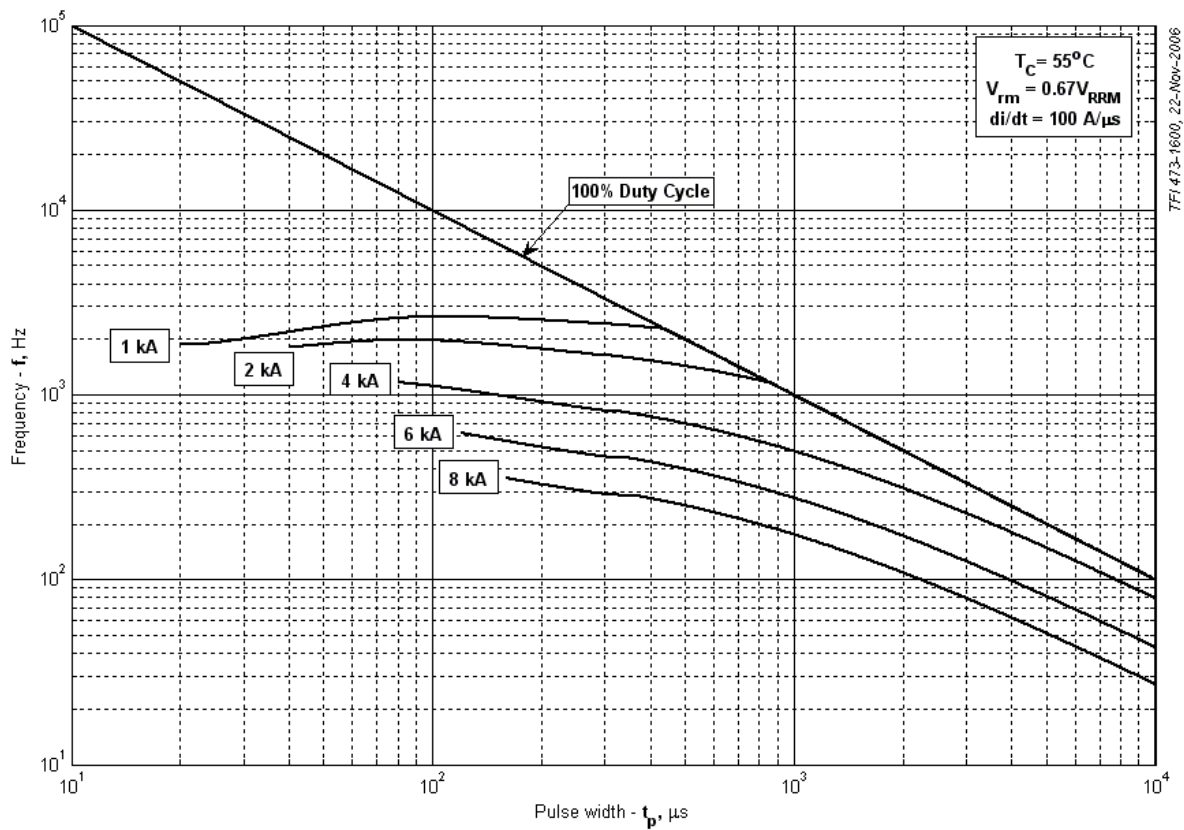
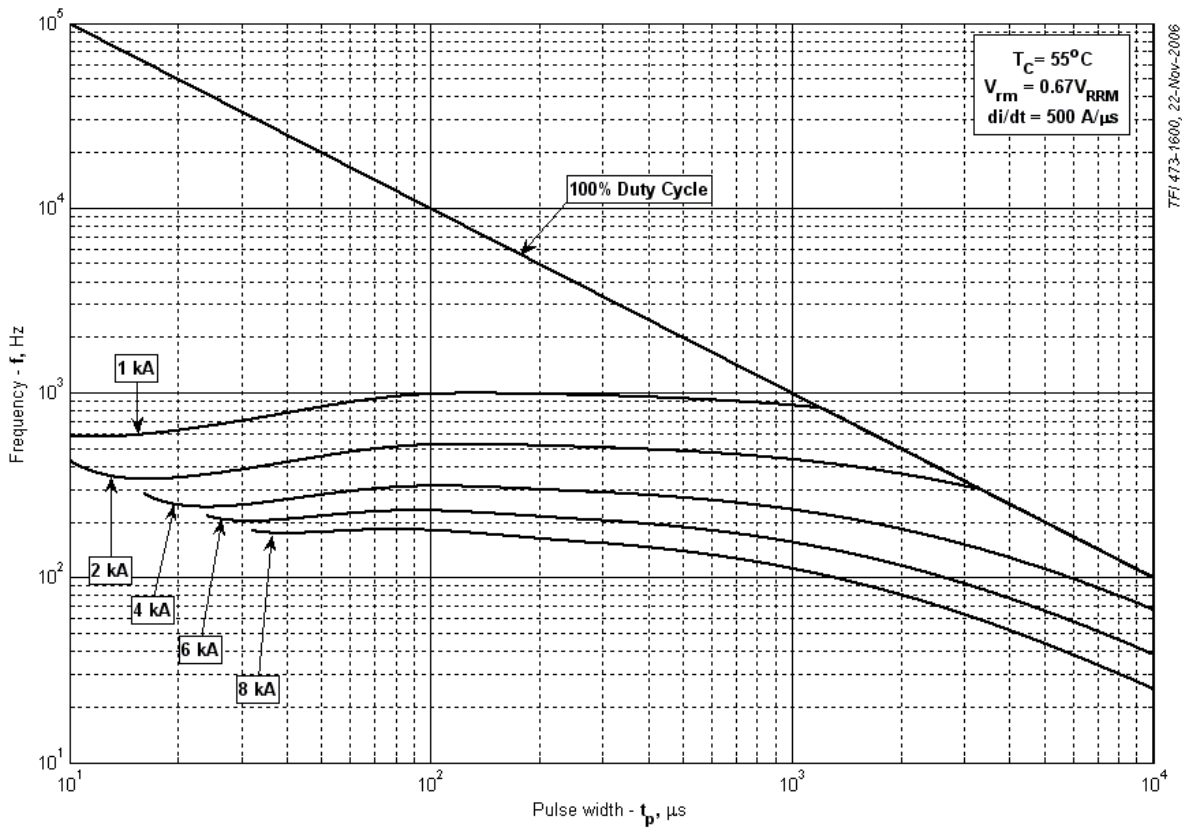
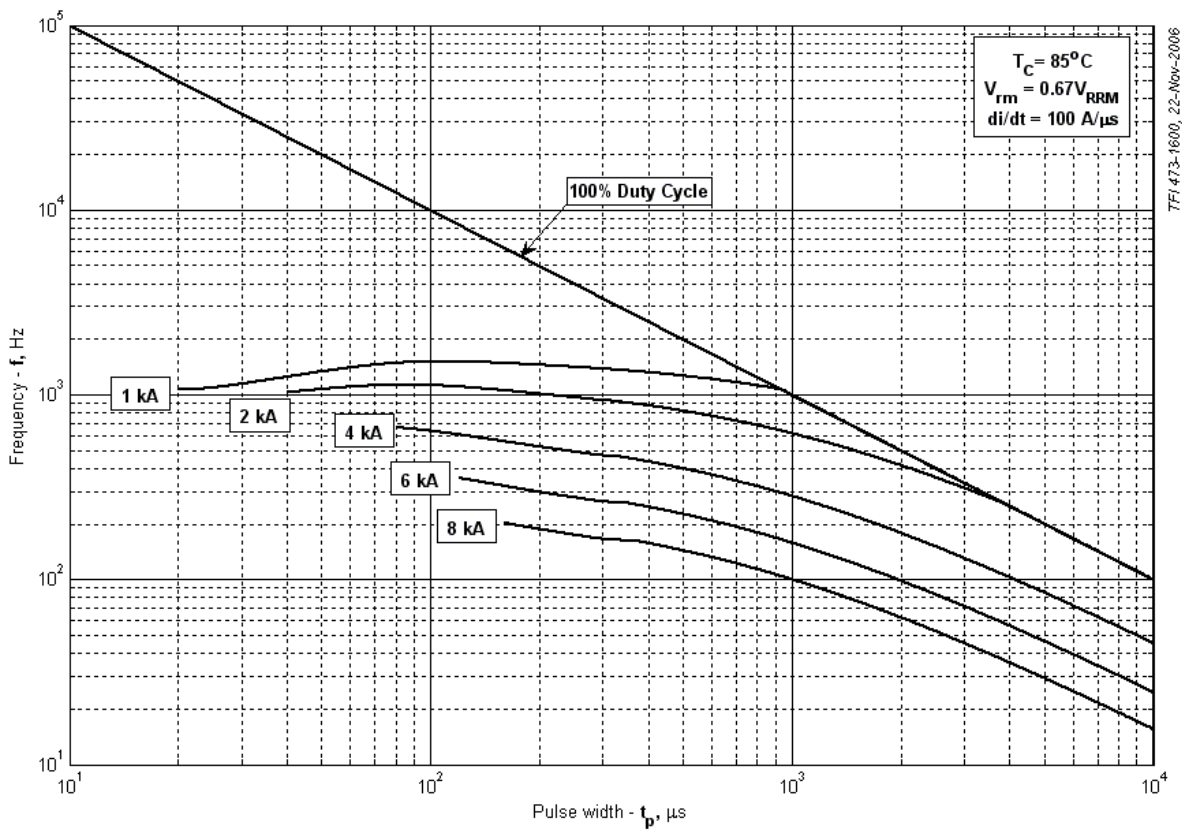


Fig 22 – Square wave frequency ratings



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Fig 23 – Square wave frequency ratings



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Fig 24 – Square wave frequency ratings

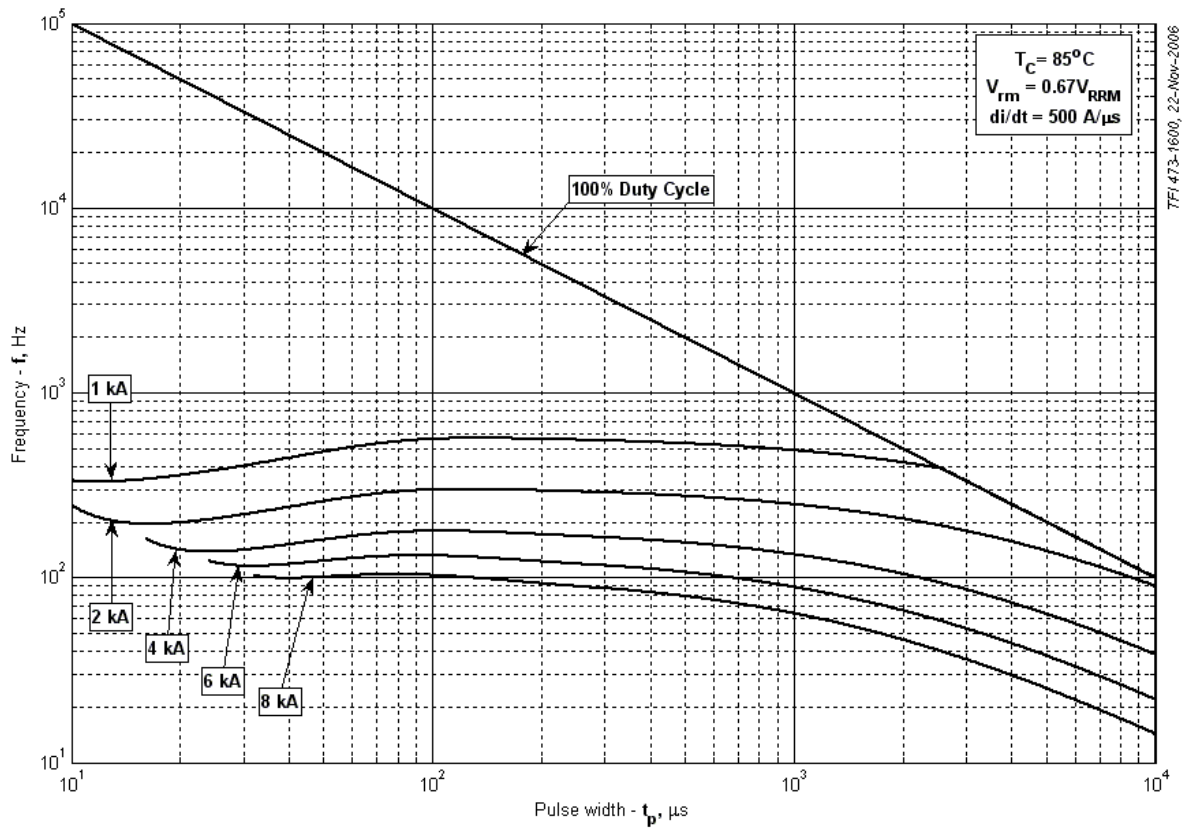


Fig 25 – Square wave frequency ratings

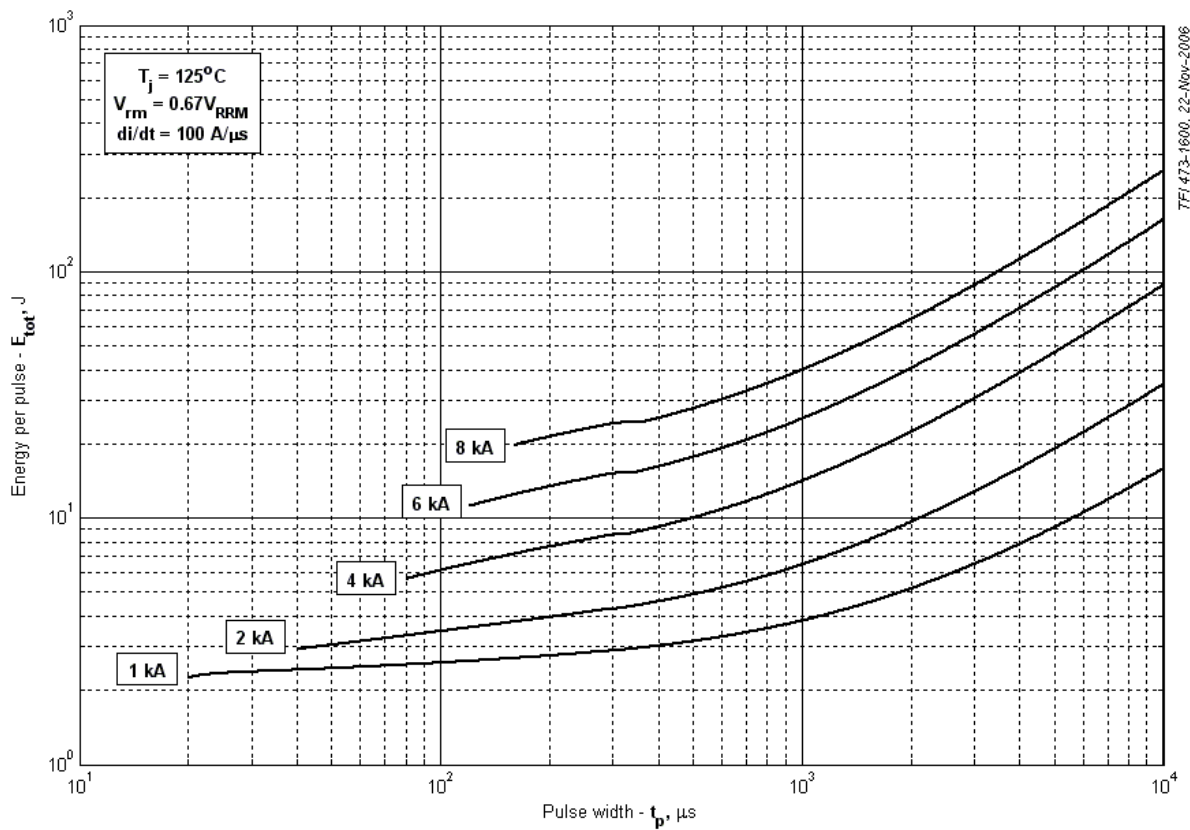


Fig 26 – Square wave energy per pulse

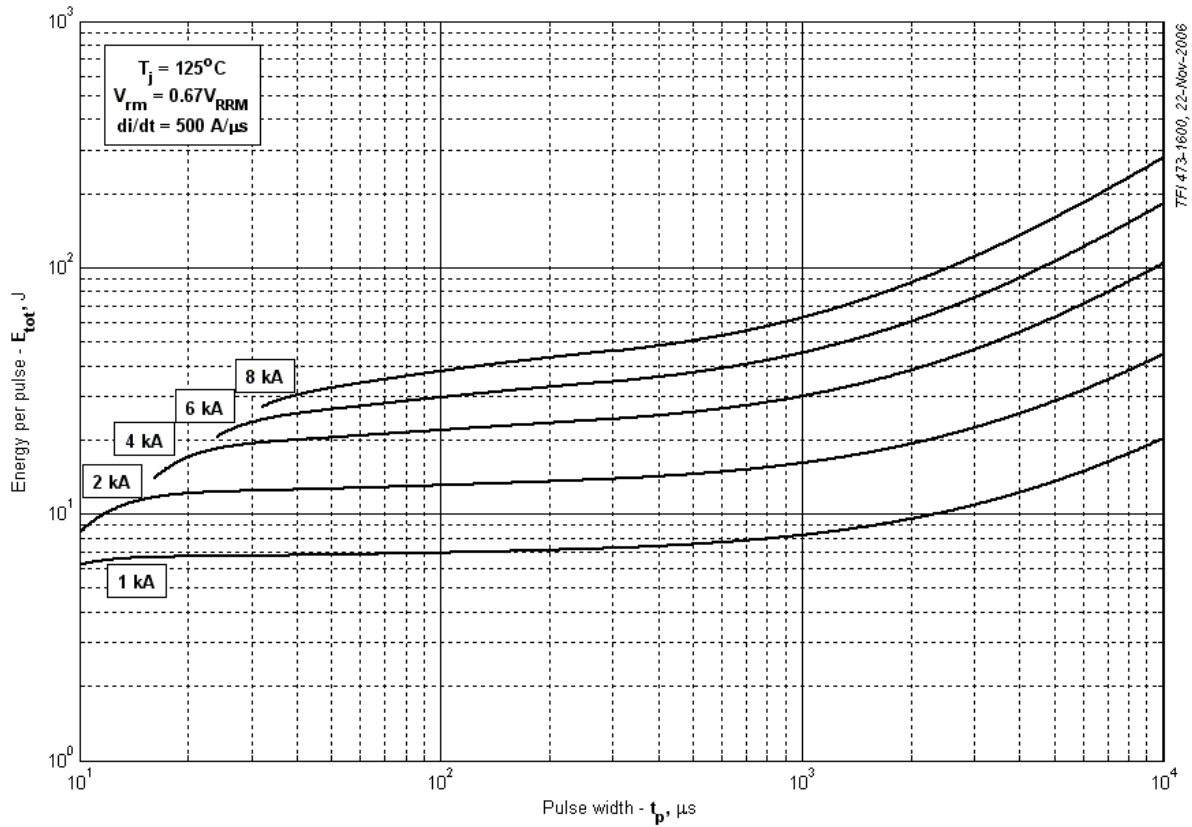


Fig 27 – Square wave energy per pulse

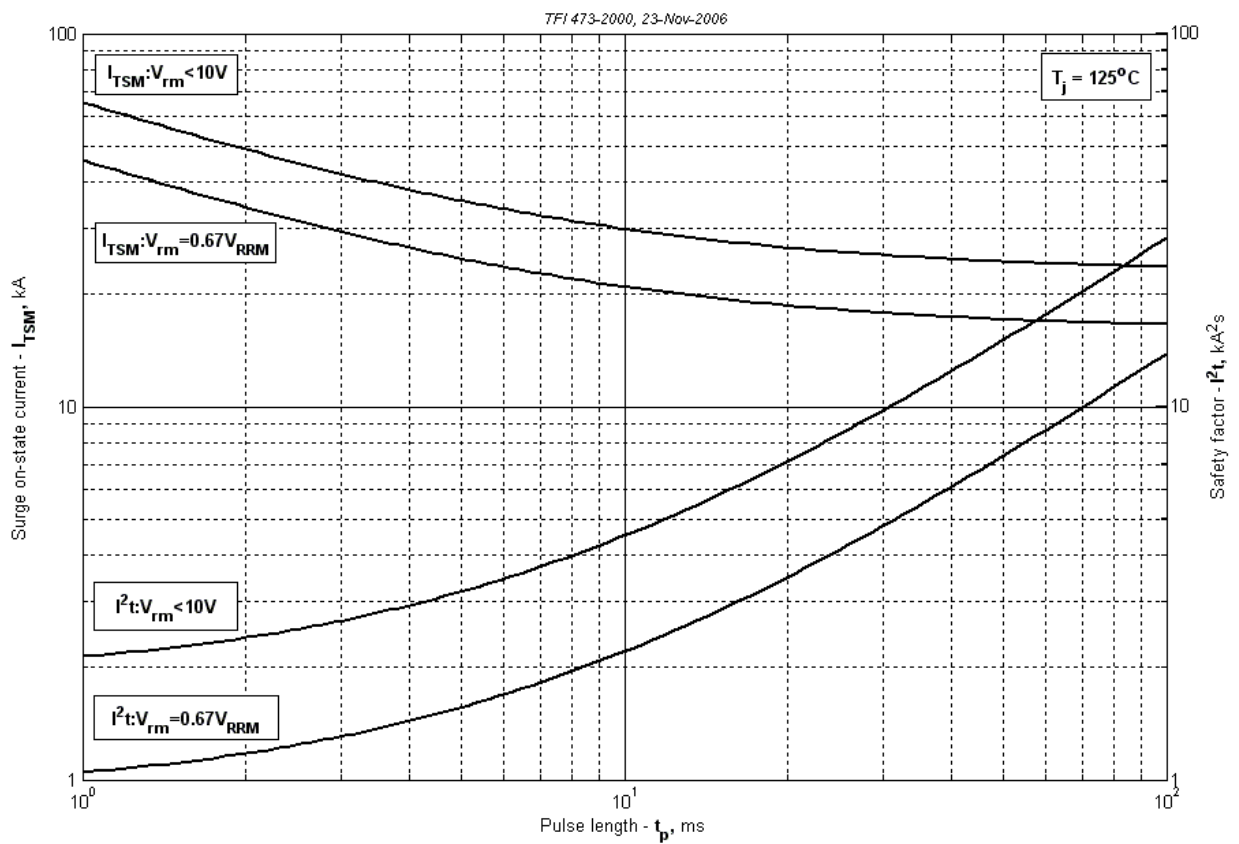


Fig 29 – Maximum surge and I^2t ratings

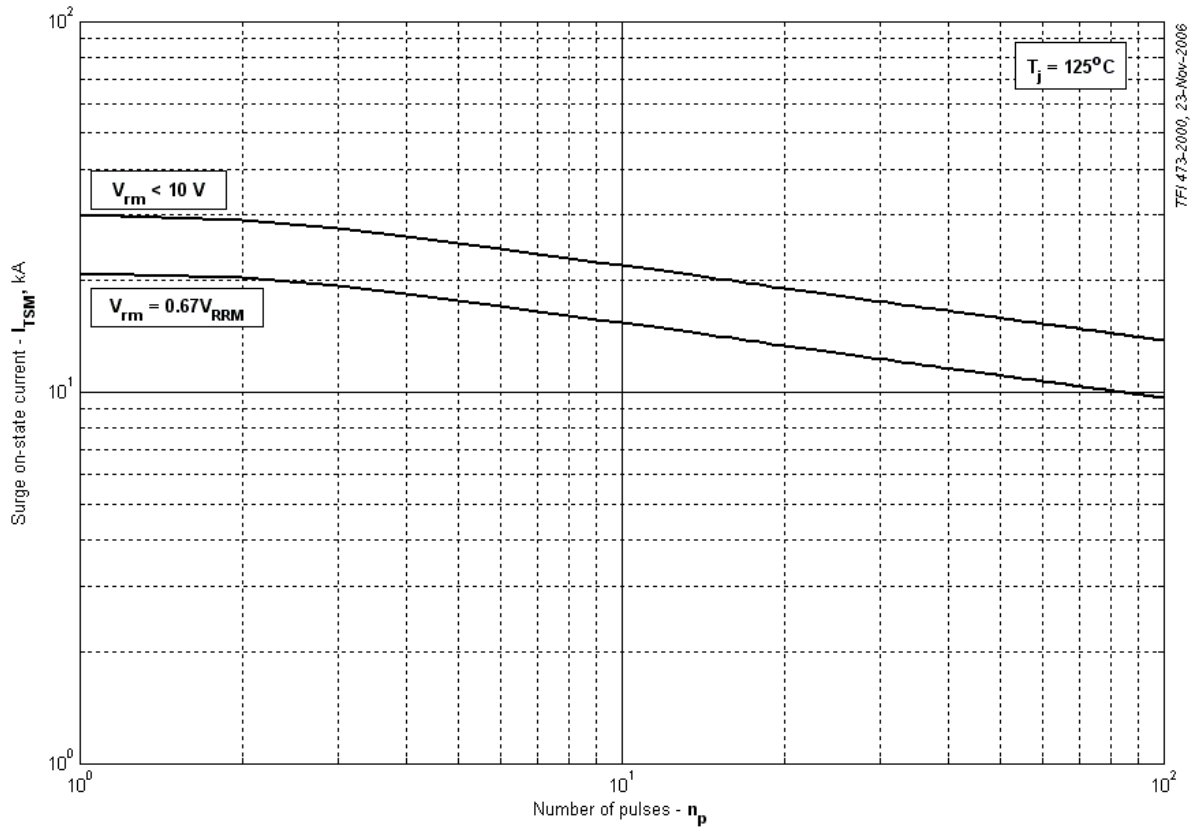


Fig 30 – Maximum surge ratings